Cohu®

Krypton™

Inspection & Metrology Platform for Large Semiconductor Packages

Next Generation Package Inspection Platform

- Saves IC devices manufacturers' inspection & metrology equipment 30% in capital expense, resulting in higher productivity.
- Increases throughput with innovative racing track technology and automatic yield recovery.
- Tray to Tape and reel and Tray to Tray process.
- Leaded, non-leaded packages QFN, QFP, BGA.
- 2 x 2 mm to 42.5 x 42.5 mm: up to 21,000 UPH including inspection.
- < 10 minutes automated conversion.
- Yield gain with Artificial Intelligence deep learning.
- Industry 4.0 AGV, OHT compatible Tray I/O.
- NV-Core™ Inspection System provides 6-sided, 3D inspection & metrology with micro-scale defect detection.
- PAICe Digital Twin Platform™ provides real-time equipment monitoring and data analytics for increased productivity.

Krypton

Package Inspection & Metrology
Tray to Tray and Tray to Tape

Up to 30% Higher Productivity

- Tray to Tape up to 21,000 UPH, Tray to Tray up to 16,000 UPH
- Featuring continuous-production race-track transfer technology with:
  - Direct sort of good and defective device for optimized throughput
  - Automatic second pass re-inspection for yield recovery
  - Micro-scale defect detection, 6-sided visible and infrared inspection, 3D Max vision system, and AI deep learning algorithms enabling pattern recognition and precise defect classification.
- Automation compatible solutions supporting factory automation and Industry 4.0.
- Semi-automated fast conversion, less than 10 minutes. Kit-less inspection stations.
- Footprint designed for floor space optimization less than 5 square meters.
- Extended scope of work to small devices in JEDEC tray down to 2 x 2 mm and larger devices up to 42.5 mm x 42.5 mm.

Cohu®

NV-Core™

Inspection System

- Full 6-sided single unit post testing inspection and metrology
- Visible and infrared inspection capability
- True 3D measurement at 6 µm repeatability
- Micro-scale defect detection down to 20 µm
- Full 1D or 2D ID unit-level traceability from tray input to tape & reel and tray output
- Vision assisted accurate device placement

NV-Core™
INSPECTION SYSTEM

PAICe™

Digital Twin Platform

- Real-time equipment monitoring and management
- Preventative maintenance
- Central recipe management
- Optimized yield and defect detection through real-time Artificial Intelligence inspection
- Knowledge database and unified reports

PAICe
DIGITAL TWIN PLATFORM™

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